

# International **IR** Rectifier

## POWER MOSFET THRU-HOLE (MO-036AB)

### Product Summary

Part Number	R <sub>D</sub> S(on)	I <sub>D</sub>
IRFG110	0.7 Ω	1.0A

HEXFET® MOSFET technology is the key to International Rectifier's advanced line of power MOSFET transistors. The efficient geometry design achieves very low on-state resistance combined with high transconductance. HEXFET transistors also feature all of the well-established advantages of MOSFETs, such as voltage control, very fast switching, ease of paralleling and electrical parameter temperature stability. They are well-suited for applications such as switching power supplies, motor controls, inverters, choppers, audio amplifiers, high energy pulse circuits, and virtually any application where high reliability is required. The HEXFET transistor's totally isolated package eliminates the need for additional isolating material between the device and the heatsink. This improves thermal efficiency and reduces drain capacitance.

PD-90396H

**IRFG110**  
**JANTX2N7334**  
**JANTXV2N7334**  
**REF: MIL-PRF-19500/597**  
**100V, QUAD N-CHANNEL**  
**HEXFET® MOSFET TECHNOLOGY**



### Features:

- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed
- Electrically Isolated
- Dynamic dv/dt Rating
- Light-weight

### Absolute Maximum Ratings

	Parameter		Units
I <sub>D</sub> @ V <sub>GS</sub> = 10V, T <sub>C</sub> = 25°C	Continuous Drain Current	1.0	A
I <sub>D</sub> @ V <sub>GS</sub> = 10V, T <sub>C</sub> = 100°C	Continuous Drain Current	0.6	
I <sub>DM</sub>	Pulsed Drain Current ①	4.0	W
P <sub>D</sub> @ T <sub>C</sub> = 25°C	Max. Power Dissipation	1.4	
	Linear Derating Factor	0.011	W/C
V <sub>GS</sub>	Gate-to-Source Voltage	±20	V
E <sub>AS</sub>	Single Pulse Avalanche Energy ②	75	mJ
I <sub>AR</sub>	Avalanche Current ①	1.0	A
E <sub>AR</sub>	Repetitive Avalanche Energy ①	0.14	mJ
dv/dt	Peak Diode Recovery dv/dt ③	5.5	V/ns
T <sub>J</sub>	Operating Junction	-55 to 150	°C
T <sub>STG</sub>	Storage Temperature Range		
	Lead Temperature	300 (0.63 in./1.6 mm from case for 10s)	g
	Weight	1.3 (Typical)	

For footnotes refer to the last page

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**Electrical Characteristics @  $T_j = 25^\circ\text{C}$  (Unless Otherwise Specified)**

	Parameter	Min	Typ	Max	Units	Test Conditions
$\text{BV}_{\text{DSS}}$	Drain-to-Source Breakdown Voltage	100	—	—	V	$\text{V}_{\text{GS}} = 0\text{V}$ , $\text{I}_D = 1.0\text{mA}$
$\Delta \text{BV}_{\text{DSS}}/\Delta T_j$	Temperature Coefficient of Breakdown Voltage	—	0.13	—	V/ $^\circ\text{C}$	Reference to $25^\circ\text{C}$ , $\text{I}_D = 1.0\text{mA}$
$\text{R}_{\text{DS(on)}}$	Static Drain-to-Source On-State Resistance	—	—	0.7	$\Omega$	$\text{V}_{\text{GS}} = 10\text{V}$ , $\text{I}_D = 0.6\text{A}$ ④
		—	—	0.8		$\text{V}_{\text{GS}} = 10\text{V}$ , $\text{I}_D = 1.0\text{A}$
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	2.0	—	4.0	V	$\text{V}_{\text{DS}} = \text{V}_{\text{GS}}$ , $\text{I}_D = 250\mu\text{A}$
$\text{g}_{\text{fs}}$	Forward Transconductance	0.86	—	—	S	$\text{V}_{\text{DS}} > 15\text{V}$ , $\text{I}_{\text{DS}} = 0.6\text{A}$ ④
$\text{I}_{\text{DSS}}$	Zero Gate Voltage Drain Current	—	—	25	$\mu\text{A}$	$\text{V}_{\text{DS}} = 80\text{V}$ , $\text{V}_{\text{GS}} = 0\text{V}$
		—	—	250		$\text{V}_{\text{DS}} = 80\text{V}$ , $\text{V}_{\text{GS}} = 0\text{V}$ , $T_j = 125^\circ\text{C}$
$\text{I}_{\text{GSS}}$	Gate-to-Source Leakage Forward	—	—	100	$\text{nA}$	$\text{V}_{\text{GS}} = 20\text{V}$
$\text{I}_{\text{GSS}}$	Gate-to-Source Leakage Reverse	—	—	-100		$\text{V}_{\text{GS}} = -20\text{V}$
$\text{Q}_g$	Total Gate Charge	—	—	15	$\text{nC}$	$\text{V}_{\text{GS}} = 10\text{V}$ , $\text{I}_D = 1.0\text{A}$
$\text{Q}_{\text{gs}}$	Gate-to-Source Charge	—	—	7.5		$\text{V}_{\text{DS}} = 50\text{V}$
$\text{Q}_{\text{gd}}$	Gate-to-Drain ('Miller') Charge	—	—	7.5		
$t_{\text{d(on)}}$	Turn-On Delay Time	—	—	20	$\text{ns}$	$\text{V}_{\text{DD}} = 50\text{V}$ , $\text{I}_D = 1.0\text{A}$ , $\text{V}_{\text{GS}} = 10\text{V}$ , $\text{R}_G = 7.5\Omega$
$t_r$	Rise Time	—	—	25		
$t_{\text{d(off)}}$	Turn-Off Delay Time	—	—	40		
$t_f$	Fall Time	—	—	40		
$\text{L}_{\text{S}} + \text{L}_{\text{D}}$	Total Inductance	—	10	—	nH	Measured from drain lead (6mm/0.25in. from package) to source lead (6mm/0.25in. from package)
$\text{C}_{\text{iss}}$	Input Capacitance	—	180	—	$\text{pF}$	$\text{V}_{\text{GS}} = 0\text{V}$ , $\text{V}_{\text{DS}} = 25\text{V}$ $f = 1.0\text{MHz}$
$\text{C}_{\text{oss}}$	Output Capacitance	—	82	—		
$\text{C}_{\text{rss}}$	Reverse Transfer Capacitance	—	15	—		

**Source-Drain Diode Ratings and Characteristics**

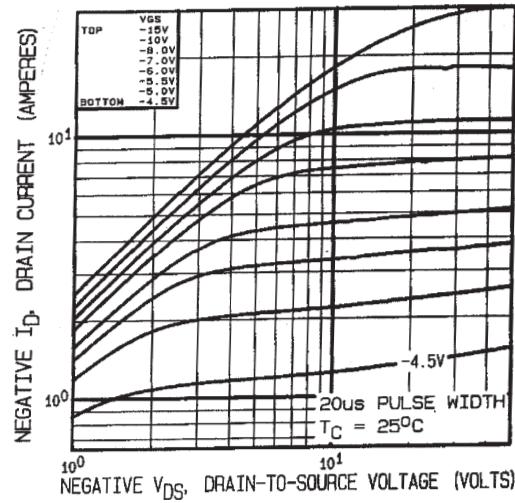
	Parameter	Min	Typ	Max	Units	Test Conditions
$\text{I}_{\text{S}}$	Continuous Source Current (Body Diode)	—	—	1.0	A	
$\text{I}_{\text{SM}}$	Pulse Source Current (Body Diode) ④	—	—	4.0		
$\text{V}_{\text{SD}}$	Diode Forward Voltage	—	—	1.5	V	$T_j = 25^\circ\text{C}$ , $\text{I}_{\text{S}} = 1.0\text{A}$ , $\text{V}_{\text{GS}} = 0\text{V}$ ④
$\text{t}_{\text{rr}}$	Reverse Recovery Time	—	—	200	ns	$T_j = 25^\circ\text{C}$ , $\text{I}_{\text{F}} = 1.0\text{A}$ , $\text{dI}/\text{dt} \leq 100\text{A}/\mu\text{s}$ $\text{V}_{\text{DD}} \leq 30\text{V}$ ④
$\text{Q}_{\text{RR}}$	Reverse Recovery Charge	—	—	0.83	$\mu\text{C}$	
$t_{\text{on}}$	Forward Turn-On Time	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by $\text{L}_{\text{S}} + \text{L}_{\text{D}}$ .				

**Thermal Resistance**

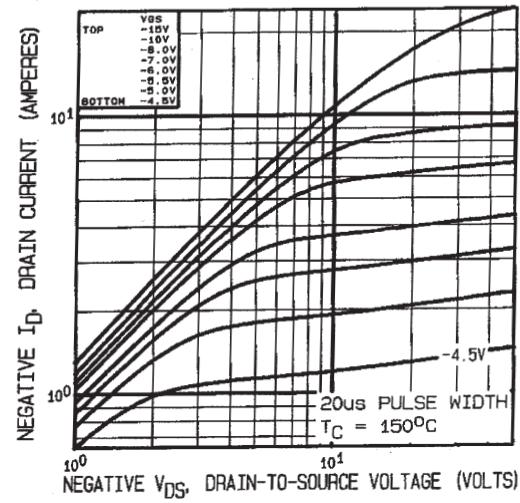
	Parameter	Min	Typ	Max	Units	Test Conditions
$\text{R}_{\text{thJC}}$	Junction-to-Case	—	—	17	$^\circ\text{C}/\text{W}$	Typical socket mount
$\text{R}_{\text{thJA}}$	Junction-to-Ambient	—	—	90		

**Note: Corresponding Spice and Saber models are available on International Rectifier Website.**

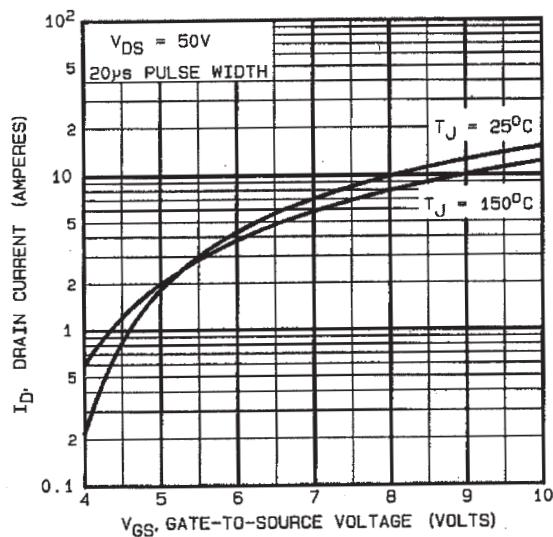
For footnotes refer to the last page



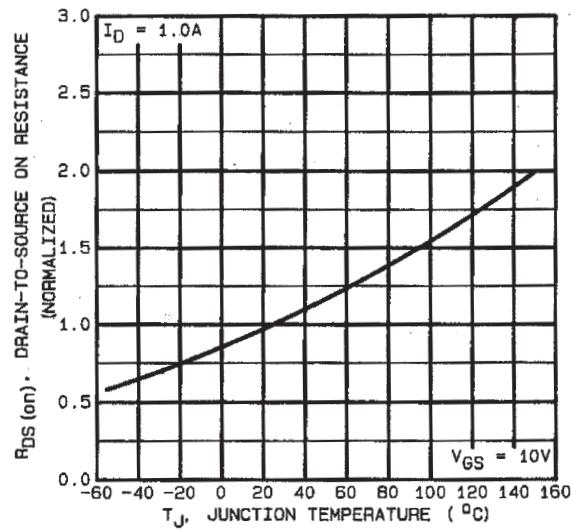
**Fig 1.** Typical Output Characteristics



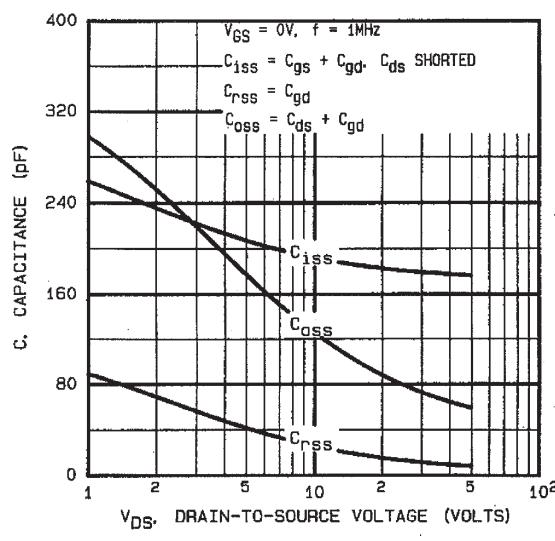
**Fig 2.** Typical Output Characteristics



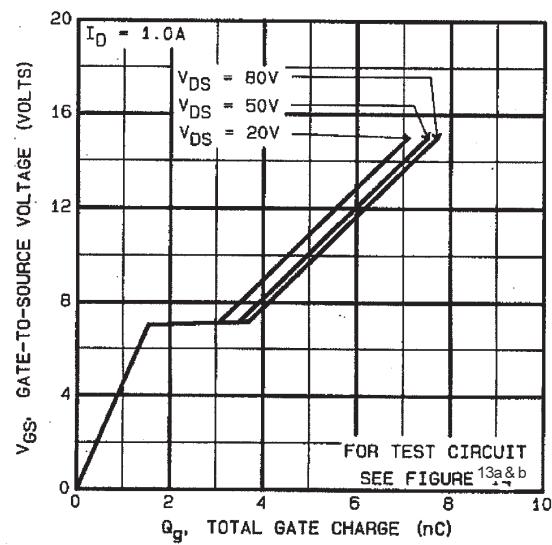
**Fig 3.** Typical Transfer Characteristics



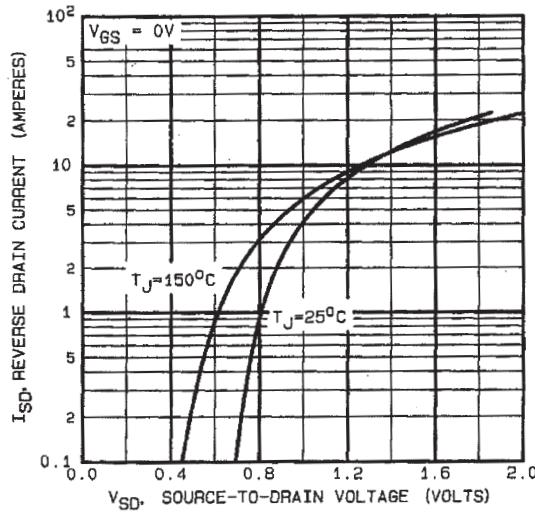
**Fig 4.** Normalized On-Resistance  
Vs. Temperature



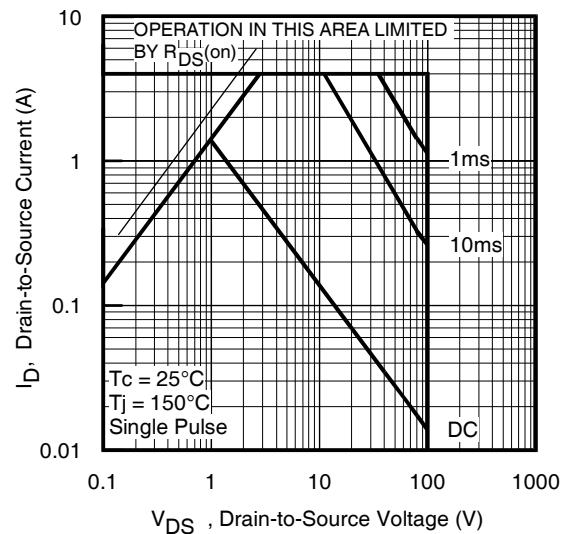
**Fig 5.** Typical Capacitance Vs.  
Drain-to-Source Voltage



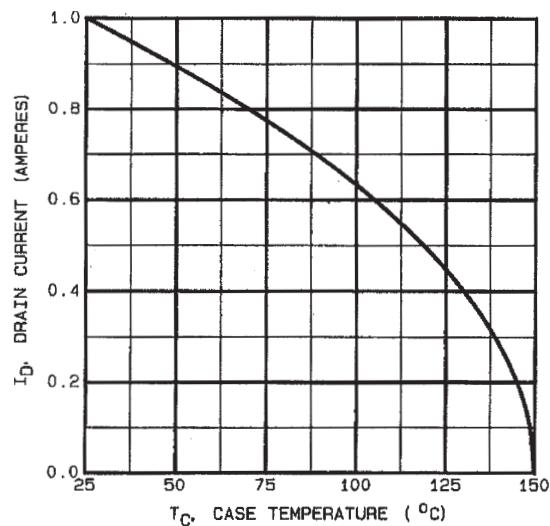
**Fig 6.** Typical Gate Charge Vs.  
Gate-to-Source Voltage



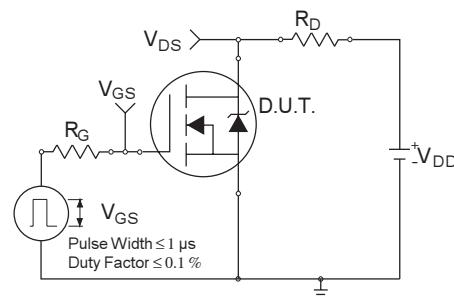
**Fig 7.** Typical Source-Drain Diode  
Forward Voltage



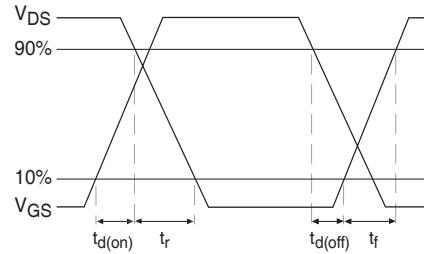
**Fig 8.** Maximum Safe Operating Area



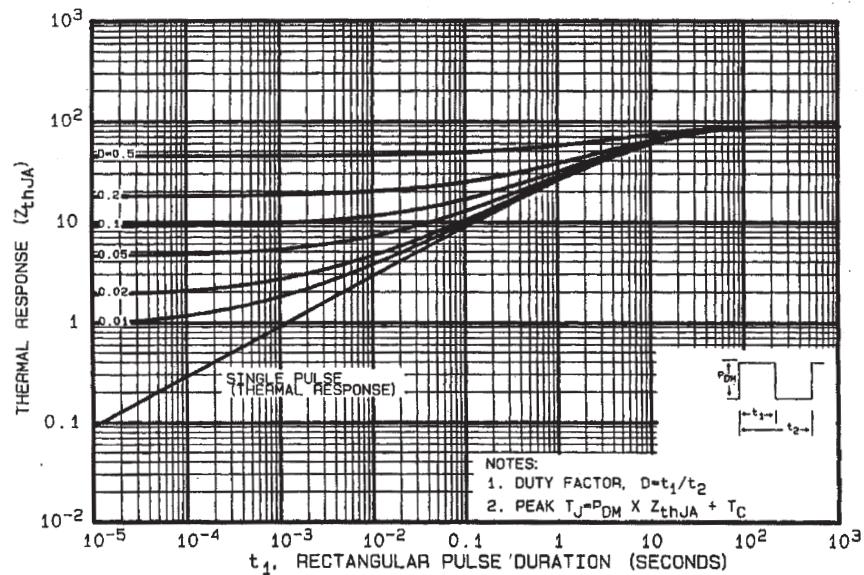
**Fig 9.** Maximum Drain Current Vs.  
Case Temperature



**Fig 10a.** Switching Time Test Circuit



**Fig 10b.** Switching Time Waveforms



**Fig 11.** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

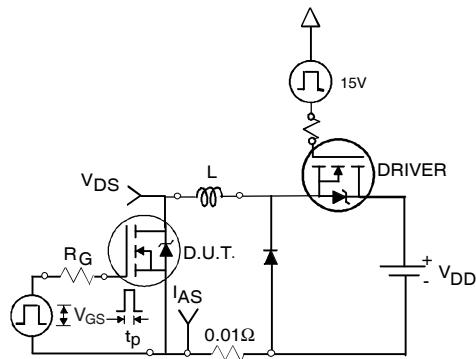


Fig 12a. Unclamped Inductive Test Circuit

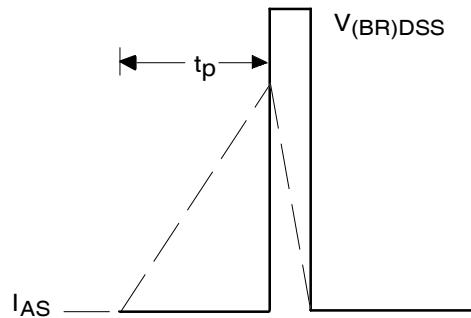
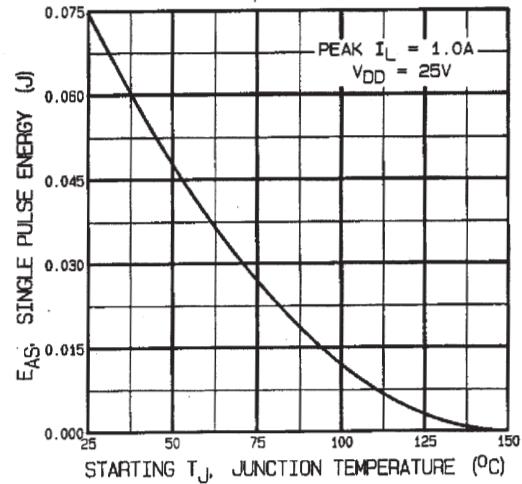


Fig 12b. Unclamped Inductive Waveforms

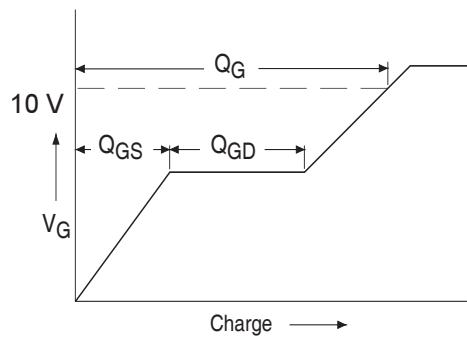


Fig 13a. Basic Gate Charge Waveform

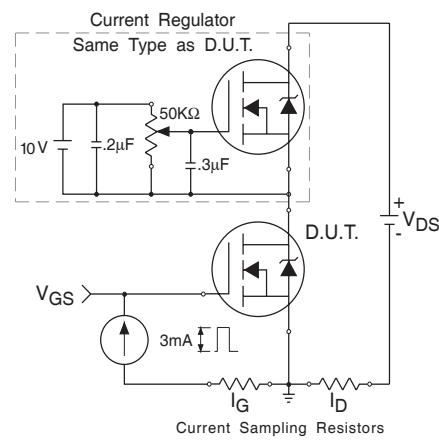


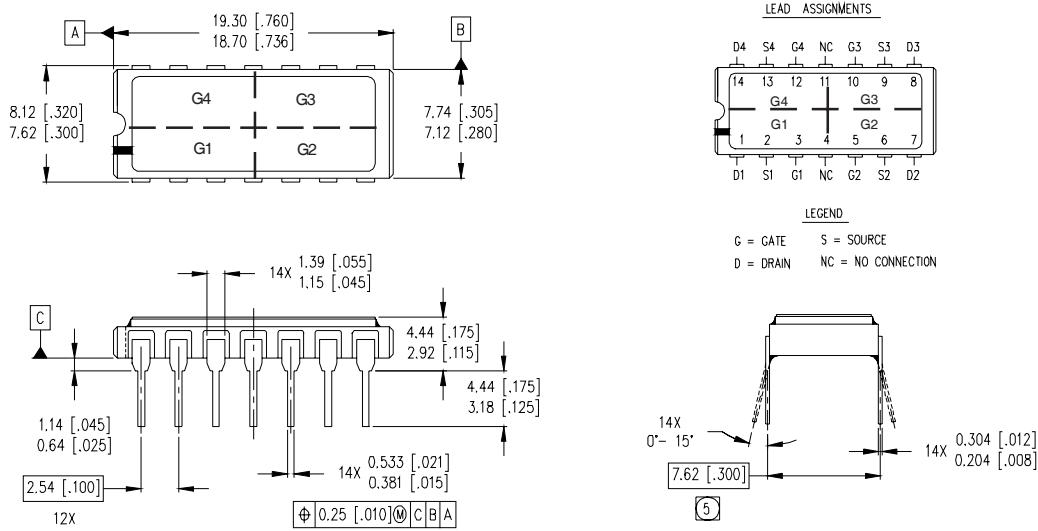
Fig 13b. Gate Charge Test Circuit

**Footnotes:**

① Repetitive Rating; Pulse width limited by maximum junction temperature.  
 ② V<sub>DD</sub> = 25V, starting T<sub>J</sub> = 25°C, L = 150mH  
 Peak I<sub>L</sub> = 1.0A, V<sub>GS</sub> = 10V

③ I<sub>SD</sub> ≤ 1.0A, di/dt ≤ 75A/μs,  
 V<sub>DD</sub> ≤ 100V, T<sub>J</sub> ≤ 150°C  
 ④ Pulse width ≤ 300 μs; Duty Cycle ≤ 2%

**Case Outline and Dimensions — MO-036AB**



NOTES:

1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
4. OUTLINE CONFORMS TO JEDEC OUTLINE MO-036AB.
5. MEASURED WITH THE LEADS CONSTRAINED TO BE PERPENDICULAR TO DATUM PLANE C.

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*Data and specifications subject to change without notice. 03/2010*